Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

06/14/2022

### Details for "DS92LV040ATLQA/NOPB"

## **Current Product Information**

| TI part number      | Lead finish/Ball material | MSL rating/peak reflow | Assembly site                 | Package   Pins | Package body size (mm) | Total device mass (mg)* |
|---------------------|---------------------------|------------------------|-------------------------------|----------------|------------------------|-------------------------|
| DS92LV040ATLQA/NOPB | SN                        | Level-2-260C-1 YEAR    | Texas Instruments Electronics | NJN   44       | 7 x 7 x 0.8            | 110.3                   |

### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

## **Environmental Ratings Information**

| RoHS | REACH | Green | IEC 62474 DB |
|------|-------|-------|--------------|
| Yes  | Yes   | Yes   | Yes          |

### Component Information

|                                    |                       |            |             | Homogeneous Material Level |         | Component Level |         |
|------------------------------------|-----------------------|------------|-------------|----------------------------|---------|-----------------|---------|
| Component                          | Substance             | CAS Number | Amount (mg) | Percentage %               | ppm     | Percentage %    | ppm     |
| Bond Wire                          |                       |            |             |                            |         |                 |         |
| Copper and Its Alloys              | Copper                | 7440-50-8  | 0.619064    | 98.733975                  | 987340  | 0.561048        | 5610    |
| Nickel and Its Alloys              | Nickel                | 7440-02-0  | 0.000003    | 0.000478                   | 5       | 0.000003        | 0       |
| Not Categorized                    | Proprietary Materials |            | 0.000069    | 0.011005                   | 110     | 0.000063        | 1       |
| Precious Metals                    | Gold                  | 7440-57-5  | 0.000135    | 0.021531                   | 215     | 0.000122        | 1       |
| Precious Metals                    | Palladium             | 7440-05-3  | 0.007713    | 1.23014                    | 12301   | 0.00699         | 70      |
| Precious Metals                    | Silver                | 7440-22-4  | 0.000018    | 0.002871                   | 29      | 0.000016        | 0       |
| Sub-Total                          |                       |            | 0.627002    | 100                        | 1000000 | 0.568242        | 5682    |
| Die Attach Adhesive                |                       |            |             |                            |         |                 |         |
| Precious Metals                    | Silver                | 7440-22-4  | 0.707442    | 75                         | 750000  | 0.641144        | 6411    |
| Thermoplastics                     | Epoxy                 | 85954-11-6 | 0.235814    | 25                         | 250000  | 0.213715        | 2137    |
| Sub-Total                          |                       |            | 0.943256    | 100                        | 1000000 | 0.854859        | 8549    |
| Lead Frame                         |                       |            |             |                            |         |                 |         |
| Copper and Its Alloys              | Copper                | 7440-50-8  | 44.709933   | 95.87                      | 958700  | 40.51993        | 405199  |
| Copper and Its Alloys              | Iron                  | 7439-89-6  | 1.10061     | 2.360001                   | 23600   | 0.997466        | 9975    |
| Copper and Its Alloys              | Phosphorus            | 7723-14-0  | 0.013991    | 0.03                       | 300     | 0.01268         | 127     |
| Precious Metals                    | Silver                | 7440-22-4  | 0.755503    | 1.62                       | 16200   | 0.684701        | 6847    |
| Zinc and Its Alloys                | Zinc                  | 7440-66-6  | 0.055963    | 0.12                       | 1200    | 0.050718        | 507     |
| Sub-Total                          |                       |            | 46.636      | 100                        | 1000000 | 42.265495       | 422655  |
| Lead Frame Plating                 |                       |            |             |                            |         |                 |         |
| Other Nonferrous Metals and Alloys | Tin                   | 7440-31-5  | 2.665       | 100                        | 1000000 | 2.415249        | 24152   |
| Sub-Total                          |                       |            | 2.665       | 100                        | 1000000 | 2.415249        | 24152   |
| Mold Compound                      |                       |            |             |                            |         |                 |         |
| Other Inorganic Materials          | Fused Silica          | 60676-86-0 | 51.673552   | 90.499999                  | 905000  | 46.830951       | 468310  |
| Thermoplastics                     | Epoxy                 | 85954-11-6 | 5.424296    | 9.500001                   | 95000   | 4.915957        | 49160   |
| Sub-Total                          |                       |            | 57.097848   | 100                        | 1000000 | 51.746908       | 517469  |
| Semiconductor Device               |                       |            |             |                            |         |                 |         |
| Ceramics / Glass                   | Doped Silicon         | 7440-21-3  | 2.371493    | 100                        | 1000000 | 2.149248        | 21492   |
| Sub-Total                          |                       |            | 2.371493    | 100                        | 1000000 | 2.149248        | 21492   |
| Total                              |                       |            | 110.340599  |                            |         | 100             | 1000000 |

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

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Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/14/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully soldered at high temperatures, TI semiconductor products labeled as "RoHS Cor compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm